Integrated Circuits (ICs)

- Integrated Circuit (IC) = “chip”
  - General-purpose microprocessor, CPU
  - Application-Specific Instruction Set Processor (ASIP), e.g. video processor or digital signal processor
  - Application-Specific IC (ASIC) or Field-Programmable Logic Device (FPLD)

- IC package contains:
  - silicon chip = “die”
  - Pins, wires between die and pins

![Figure from Application-Specific Integrated Circuits, Smith, Addison-Wesley, 1997]

- Package may have heat sink attached

Some Applications of ICs

- Home
  - Appliances, intercom, telephones, security system, garage door opener, answering machines, fax machines, home computers, TVs, cable TV tuner, VCR, camcorder, video games, cellular phones, sewing machines, cameras, exercise equipment, microwave oven

- Office
  - Telephones, computers, security system, fax machines, copier, printers, pagers

- Automobile
  - Trip computer, air bags, ABS, instrumentation, security system, transmission control, entertainment system, climate control, keyless entry, cellular phone, GPS

List from Hardware/Software Codesign, Giovanni De Micheli, 1996.

Integrated Circuits (ICs) (cont.)

- A modern digital system is built out of a collection of integrated circuits (ICs), each of which is made up of gates

- ICs are typically classified based on the number of gates they contain
  - SSI (small scale integration) < 10
    - 4 nand gates
    - 4 or gates
    - 4 and gates
  - MSI (medium…) 10-100
    - simple adders, counters
    - multiplexers
    - flip-flops
  - LSI (large…) 100-10,000
    - Interface devices
    - Calculators
    - Digital clocks
    - Simple microprocessors

Integrated Circuits (ICs) (cont.)

- Classification, cont.
  - VLSI (very large…) >10,000
    - Modern microprocessors
      - 8086 = 29,000
      - i386DX = 275,000
      - i486DX = 1,200,000
      - Pentium = 3,100,000
      - Pentium Pro = 5,500,000
      - Pentium II = 7,500,000
      - Pentium M = 77,000,000 (half are for the L2 cache)
  - Application-Specific Instruction Set Processor (ASIP), e.g. video processor or digital signal processor
  - Application-Specific IC (ASIC)
    - Generally cost-effective only when produced in high volume (hundreds of thousands of part)
    - Also used when very high performance is needed
  - Field-Programmable Logic Device (FPLD)
    - Very common, 80,000 new design starts in 2003 (vs. 4,000 for ASICs)
**ASICS vs. FPLDs**

- IC contains a *chip* ("die") cut from a *wafer*
  - Transistors, wires, etc. are built up on the chip in a series of *layers* (10-50 layers)
  - A *mask* is used to define the components of a layer as they are applied to the chip
- **ASICS vs. FPLDs** (+ pizza equivalent)
  - Full-custom ASIC
    - Prepare pizza sauce, toppings, dough from scratch; takes a long time
  - Standard-cell-based ASIC
    - Choose from limited selection of toppings and dough; less work but still slow
  - Gate-array-based ASIC
    - Add canned toppings to pre-cooked crusts; save some time and cost
  - Field-programmable logic device
    - Frozen pizza — limited selection, trivial to cook, very cheap

**Full-Custom ASICs**

- **Design** — engineer does detailed design of logic cells, circuit, and layout
  - Time-consuming and costly!
  - Primarily used if no pre-designed modules are available (e.g., new or highly specialized circuit), or when very high performance is needed
- **Fabrication** — design is sent to a *fabrication facility* (a "fab"), where it is etched onto *wafer*s, each wafer containing 100’s of chips
  - Wafers used to be 8", now 13", discs
  - Fabrication is expensive (huge fixed startup cost), and takes a couple of months
  - Most chips fabricated using CMOS techniques (details later in the course)

**Standard-Cell-Based ASICs**

- **Design** — chip is built from pre-defined modules called *standard cells*
  - Standard cells are built by someone else using full-custom design techniques
  - Save time, money, and risk by using a well-designed, verified *cell library*
    - But — have to pay for the cell library
  - Also use larger cells (microprocessors, etc.) called *mega cells* (sometimes *cores*)

**Standard-Cell-Based ASICs (cont.)**

- Cells fit together like bricks in a wall — rows of (variable-width) cells
  - Most interconnect goes in *channels* between rows, though some cells may be designated as *feedthroughs* (vias) between rows
  - Most *metal layers* provide interconnect
    - Others provide power and ground
  - Fabrication remains costly and slow

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Figure from *Application-Specific Integrated Circuits*, Smith, Addison-Wesley, 1997
Gate Array-Based ASICs

- Designed using pre-defined modules
- Fabrication time reduced — transistors are placed in a fixed pattern on the chip
  - Interconnect is defined by designer and fabricated using a custom mask
- Chip is partially fabricated (cells, power, etc. added) and then stockpiled
  - When design is received for fabrication, the remaining metal layers are added
  - Cheaper — everyone shares cost of producing high volume of initial chip
  - Quick turn-around — days, couple weeks
- Variations:
  - Channeled gate arrays
  - Channelless gate arrays

Programmable Logic Devices (FPLDs)

- Known by a variety of names:
  - Field-Programmable Gate Array (FPGA)
  - Field-Programmable Logic Device (FPLD)
  - Complex Programmable Logic Device (CPLD)
- Similar to PLDs, but more complex
  - Core is a regular array of programmable logic cells, each of which contains combinational and sequential logic
  - Programmable interconnect surrounds the logic cells
  - Some method provided for programming the base logic cells and the interconnect
  - Designed using pre-defined modules, with “fabrication” turn-around on the order of minutes

Field Programmable Logic Devices (FPLDs)

- Standard ICs, available in standard configurations, sold in high volume
  - No customized cells or masks, just a single large block of programmable interconnect
  - Can be configured / programmed to create a specialized device
  - Fast turn-around time
- Examples
  - Mask-programmable ROM — programmed when ordered
  - Programmable ROM — programmed electrically, erased electrically or using ultraviolet light, all by customer
  - PAL, PLA — 2-level sum-of-products and/or array, programmed electrically by customer (blowing fuses in array)

ASICs vs. FPLDs

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>ASIC</th>
<th>FPLD</th>
</tr>
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<tbody>
<tr>
<td>Time to market</td>
<td>Long</td>
<td>Short</td>
</tr>
<tr>
<td>High volume unit cost</td>
<td>Low</td>
<td>High</td>
</tr>
<tr>
<td>NRE</td>
<td>High</td>
<td>None</td>
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<tr>
<td>Flexibility after manufacturing</td>
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<tr>
<td>Performance</td>
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<td>Medium</td>
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<tr>
<td>Density</td>
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<td>Power consumption</td>
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<tr>
<td>Minimum order quantity</td>
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<tr>
<td>Design flow complexity</td>
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<tr>
<td>Complexity of testing</td>
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<td>Low</td>
</tr>
<tr>
<td>Turnaround time</td>
<td>Months</td>
<td>Hours</td>
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Source: Jack Horgan, EDA Weekly, Monday 8/9/04